

**Amendments to the Specification:**

Please amend paragraphs [0041], [0042], [0045] and [0055] as shown below.

[0041] Referring next to FIGS. 3A and 3B, in another embodiment of the invention the conductive layer 64 covers the upper surface 66a, outer wall 67 and inner wall 69 of each conductive bump 52a as viewed in the cross-section A-A of FIG. [3A] 2A. When viewed in the cross-section B-B of FIG. [3B] 2B, however, the conductive layer 64 and underlying adhesion layer 62 do not cover the sidewalls 68 of each conductive bump 52a, leaving the bump-forming layer 66 exposed on the respective sidewalls 68. Furthermore, each conductive layer 64 and adhesion layer 62 on the upper surface 66a are etched to define [a] at least one shoulder 66b which is uncovered by the conductive layer 64 and adhesion layer 62 at the edges of the upper surface 66a.

[0042] Referring next to FIGS. 4A and 4B, in still another embodiment of the invention the conductive layer 64 covers the upper surface 66a, outer wall 67 and inner wall 69 of each conductive bump 52b as viewed in the cross-section A-A of FIG. [3A] 2A. As shown in FIG. 4B, each conductive bump 52b includes one exposed sidewall 68, from which the adhesion layer 62 and conductive layer 64 are omitted, and one covered sidewall 68 on which is provided the adhesion layer 62 and the conductive layer 64. A shoulder 66b may be provided in the adhesion layer 62 and conductive layer 64, at an edge of the upper surface 66a of the conductive bump 52b.

[0045] Referring next to FIGS. 7A and 7B, in yet another embodiment each of the conductive bumps 82a includes [a] at least one shoulder 66b provided in the conductive layer 64 and underlying adhesion layer 62, at the edges of the upper surface 66a, as shown in FIG. 7B. As shown in FIG. 7A, when viewed along the cross-section A-A in FIG. 6, the adhesion layer 62 and overlying conductive layer 64 cover both the upper surface 66a and the outer wall 67 of each conductive bump 82a, whereas the inner wall 69 remains uncovered and exposed.

[0055] As shown in FIG. 12H, the portions of the conductive layer 64 and underlying adhesion layer 62 that are not covered by the photoresist 67 are then etched from the sidewalls 68 of the bump structure 99. Accordingly, as shown in FIG. 12I, the adhesion layer 62 and conductive layer 64 remain on the upper surface 66a of the conductive bump 52a, whereas the sidewalls 68 are exposed and uncovered by the adhesion layer 62 and conductive layer 64. Furthermore, by using a photoresist layer 97 (FIG. 12G) which is narrower than the upper surface

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66a of the conductive bump 52a, as shown, [a] at least one shoulder 66b [be] is provided in the conductive layer 64 and adhesion layer 62, at the edges of the upper surface 66a.